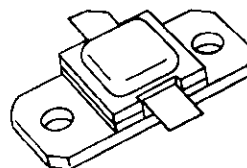


RF & MICROWAVE TRANSISTORS S-BAND RADAR APPLICATIONS

PRELIMINARY DATA

- REFRACTORY/GOLD METALLIZATION
- EMITTER SITE BALLASTED
- LOW THERMAL RESISTANCE
- INPUT/OUTPUT MATCHING
- OVERLAY GEOMETRY
- METAL/CERAMIC HERMETIC PACKAGE
- $P_{OUT} = 12\text{ W MIN. WITH } 6.0\text{ dB GAIN}$



.400 x .400 2LFL (S036)
hermetically sealed

ORDER CODE

AM82731-012

BRANDING

82731-12

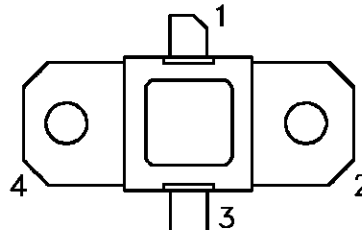
DESCRIPTION

The AM82731-012 device is a high power silicon bipolar NPN transistor specifically designed for S-Band radar pulsed output and driver applications.

This device is capable of operation over a wide range of pulse widths, duty cycles, and temperatures and can withstand a 3:1 output VSWR with a + 1 dB input overdrive. Low RF thermal resistance, refractory/gold metallization, and automatic wire bonding techniques ensure high reliability and product consistency (including phase characteristics).

The AM82731-012 is supplied in the Hermetic Metal/Ceramic package with internal Input/Output impedance matching circuitry, and is intended for military and other high reliability applications.

PIN CONNECTION



1. Collector

2. Base

3. Emitter

4. Base

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}\text{C}$)

Symbol	Parameter	Value	Unit
P_{DISS}	Power Dissipation* ($T_C \leq 50^{\circ}\text{C}$)	50	W
I_C	Device Current*	2.0	A
V_{CC}	Collector-Supply Voltage*	46	V
T_J	Junction Temperature (Pulsed RF Operation)	250	$^{\circ}\text{C}$
T_{STG}	Storage Temperature	- 65 to +200	$^{\circ}\text{C}$

THERMAL DATA

$R_{TH(j-c)}$	Junction-Case Thermal Resistance*	4.0	$^{\circ}\text{C/W}$
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*Applies only to rated RF amplifier operation

ELECTRICAL SPECIFICATIONS ($T_{case} = 25^{\circ}C$)

STATIC

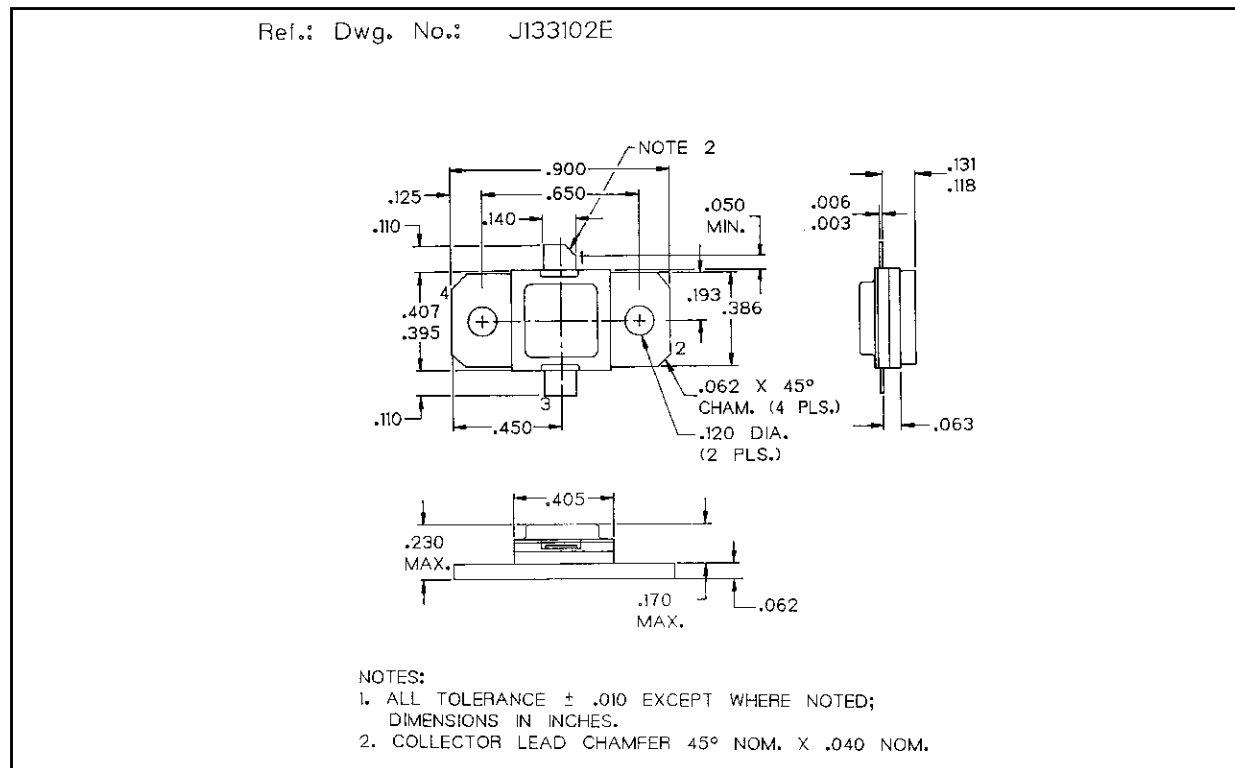
Symbol	Test Conditions	Value			Unit
		Min.	Typ.	Max.	
BV_{CBO}	$I_C = 7mA$ $I_E = 0mA$	55	—	—	V
BV_{EBO}	$I_E = 1mA$ $I_C = 0mA$	3.5	—	—	V
BV_{CER}	$I_C = 7mA$ $R_{BE} = 10\Omega$	55	—	—	V
I_{CES}	$V_{CE} = 40V$	—	—	5	mA
h_{FE}	$V_{CE} = V$ $I_C = 600mA$	30	—	300	—

DYNAMIC

Symbol	Test Conditions	Value			Unit
		Min.	Typ.	Max.	
P_{OUT}	$f = 2700 — 3100$ MHz $P_{IN} = 3.0W$ $V_{CC} = 40V$	12	—	—	W
η_c	$f = 2700 — 3100$ MHz $P_{IN} = 3.0W$ $V_{CC} = 40V$	30	—	—	%
G_P	$f = 2700 — 3100$ MHz $P_{IN} = 3.0W$ $V_{CC} = 40V$	6.0	—	—	dB

Note: Pulse Width = 100 μ S
Duty Cycle = 10%

PACKAGE MECHANICAL DATA



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